LINEAR TECHNOLOGY MATERIALS DECLARATION

lt1211acn8#pbf **(Engineering Calculation)** **PDIP**

(printed on: 2020-07-11 18:19:09) **TOTAL MASS (g): 0.500529**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.
Active Device	Linear Technology	Silicon (Si)	7440-21-3	**0.003683**	**1000000**	**7358.2109375**
Die Coat	Dow Corning	Silicone	69430-27-9	**0.000882**	**1000000**	**1762.13476562**
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.149760	975000	299203.25
		Iron (Fe)	7439-89-6	0.003686	24000	7364.20410156
		Phosphorus (P)	7723-14-0	0.000046	300	91.9027175903
		Zinc (Zn)	7440-66-6	0.000108	700	215.771591187
		Nickel (Ni)	7440-02-0	0.000000	0	0
		Silicon (Si)	7440-21-3	0.000000	0	0
		Magnesium (Mg)	7439-95-4	0.000000	0	0
		Tin (Sn)	7440-31-5	0.000000	0	0
		Lead Frame Total:		**0.153600**	**1000000**	**306875.15625**
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0
		Exter. Plating Sn	7440-31-5	0.012410	1000000	24794.3339844
		External Plating Total:		**0.012410**	**1000000**	**24794.3339844**
		Inter. Plating Ni	7440-02-0	0.000000	0	0
		Inter. Plating Ag	7440-22-4	0.001228	1000000	2453.40283203
		Internal Plating Total:		**0.001228**	**1000000**	**2453.40283203**
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001042	750000	2081.79638672
		Tin (Sn)	7440-31-5	0.000000	0	0
		Lead (Pb)	7439-92-1	0.000000	0	0
		Silica (SiO2)	60676-86-0	0.000000	0	0
		Indium (In)	7440-74-6	0.000000	0	0
		Metal Oxide		0.000000	0	0
		Antimony (Sb)	7440-36-0	0.000000	0	0
		Resin (EP)		0.000347	250000	693.266113281
		Die Attach Total:		**0.001389**	**1000000**	**2775.06225586**
Encapsulation	FILLED EPOXY RESIN	Resin (EP)		0.078520	240000	156873.9375
		Bromine (Br)	40039-93-8	0.003272	10000	6537.07958984
		Silica (SiO2)	60676-86-0	0.235561	720000	470623.78125
		Antimony Trioxide (Sb2O3)	1309-64-4	0.009815	30000	19609.2421875
		Metal Hydroxide		0.000000	0	0
		Carbon Black (C)	1333-86-4	0.000000	0	0
		Encapsulation Total:		**0.327168**	**1000000**	**653644**
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	**0.000169**	**1000000**	**337.642578125**
					TOTAL MASS (g):	**0.500529**